

PI5C3257

Quad 2:1 Mux/DeMux Bus Switch

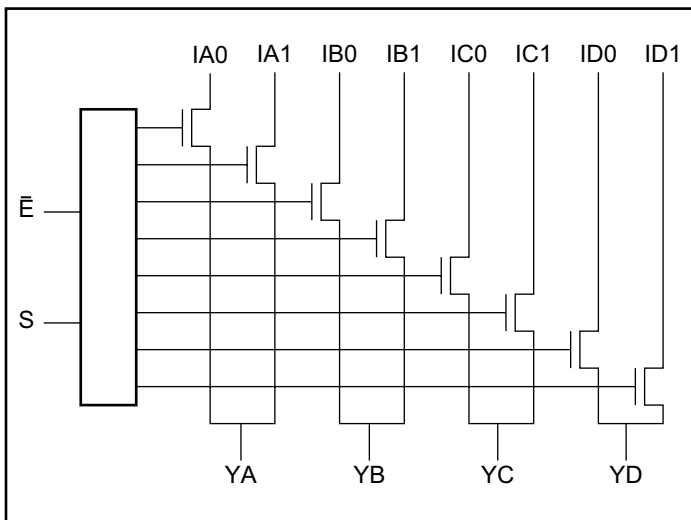
Features:

- Near-Zero propagation delay
- 5Ω switches connect inputs to outputs
- Direct bus connection when switches are ON
- Ultra Low Quiescent Power (0.2μA typical)
– Ideally suited for notebook applications
- Pin compatible with 74 series 257 logic devices
- Packaging (Pb-free & Green available):
– 16-pin 150-mil wide plastic QSOP (Q)
– 16-pin 150-mil wide plastic SOIC (W)
– 16-pin 173-mil wide plasticTSSOP (L)

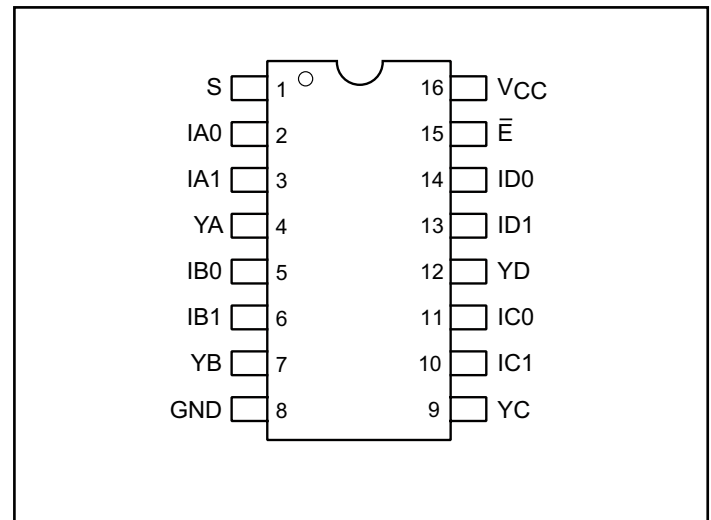
Description

The PI5C3257 is a Quad 2:1 multiplexer/demultiplexer with three-state outputs that is pinout and function compatible with the PI74FCT257T, 74F257, and 74ALS/AS/LS257. Inputs can be connected to outputs with low On-Resistance (5Ω) with no additional ground bounce noise or propagation delay.

Block Diagram



Pin Configuration



Truth Table⁽¹⁾

\bar{E}	S	YA	YB	YC	YD	Function
H	X	Hi-Z	Hi-Z	Hi-Z	Hi-Z	Disable
L	L	IA0	IB0	IC0	ID0	S = 0
L	H	IA1	IB1	IC1	ID1	S = 1

Note:

1. H = High Voltage Level, L = Low Voltage Level

Pin Description

Pin Name	Description
IA _n -ID _n	Data Inputs
S	Select Inputs
\bar{E}	Enable
YA-YD	Data Outputs
GND	Ground
V _{CC}	Power

Maximum Ratings

(Above which the useful life may be impaired. For user guidelines, not tested.)

Storage Temperature	-65°C to +150°C
Ambient Temperature with Power Applied	-40°C to +85°C
Supply Voltage to Ground Potential (Inputs & V _{CC} Only)....	-0.5V to +7.0V
Supply Voltage to Ground Potential (Outputs & D/O Only) ..	-0.5V to +7.0V
DC Input Voltage	-0.5V to +7.0V
DC Output Current.....	120mA
Power Dissipation	0.5W

Note:

Stresses greater than those listed under MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

DC Electrical Characteristics (Over the Operating Range, T_A = -40°C to +85°C, V_{CC} = 5V ±5%)

Parameters	Description	Test Conditions ⁽¹⁾	Min.	Typ. ⁽²⁾	Max.	Units
V _{IH}	Input HIGH Voltage	Guaranteed Logic HIGH Level	2.0			V
V _{IL}	Input LOW Voltage	Guaranteed Logic LOW Level	-0.5		0.8	
I _{IH}	Input HIGH Current	V _{CC} = Max., V _{IN} = V _{CC}			±1	µA
I _{IL}	Input LOW Current	V _{CC} = Max., V _{IN} = GND			±1	
I _{OZH}	High Impedance Output Current	0 ≤ I, Y ≤ V _{CC}			±1	
V _{IK}	Clamp Diode Voltage	V _{CC} = Min., I _{IN} = -18 mA		-0.7	-1.2	V
I _{OS}	Short Circuit Current ⁽³⁾	I (Y) = 0V, Y (I) = V _{CC}	100			mA
V _H	Input Hysteresis at Control Pins			150		mV
R _{ON}	Switch On-Resistance ⁽⁴⁾	V _{CC} = Min., V _{IN} = 0.0V, I _{ON} = 48mA		5	7	Ω
		V _{CC} = Min., V _{IN} = 2.4V, I _{ON} = 15mA		10	15	

Notes:

- For Max. or Min. conditions, use appropriate value specified under Electrical Characteristics for the applicable device type.
- Typical values are at V_{CC} = 5.0V, T_A = 25°C ambient and maximum loading.
- Not more than one output should be shorted at one time. Duration of the test should not exceed one second.
- Measured by the voltage drop between I and Y pin at indicated current through the switch. On-Resistance is determined by the lower of the voltages on the two (I,Y) pins.

Capacitance (T_A = 25°C, f = 1 MHz)

Parameters ⁽¹⁾	Description	Test Conditions	Typ.	Max.	Units
C _{IN}	Input Capacitance	V _{IN} = 0V		6	pF
C _{OFF}	In/Yn Capacitance, Switch Off			6	
C _{ON}	In/Yn Capacitance, Switch On			14	

Notes:

- This parameter is determined by device characterization but is not production tested.

Power Supply Characteristics

Parameters	Description	Test Conditions ⁽¹⁾		Min.	Typ. ⁽²⁾	Max.	Units
I _{CC}	Quiescent Power Supply Current	V _{CC} = Max.	V _{IN} = GND or V _{CC}		0.1	3.0	μA
ΔI _{CC}	Supply Current per Input @ TTL HIGH	V _{CC} = Max.	V _{IN} = 3.4V ⁽³⁾			2.5	mA
I _{CCD}	Supply Current per Input per MHz ⁽⁴⁾	V _{CC} = Max., I and Y Pins Open \overline{BE} = GND Control Input Toggling 50% Duty Cycle				0.25	mA/ MHz

Notes:

1. For Max. or Min. conditions, use appropriate value specified under Electrical Characteristics for the applicable device.
2. Typical values are at V_{CC} = 5.0V, +25°C ambient.
3. Per TTL driven input (V_{IN} = 3.4V, control inputs only); I and Y pins do not contribute to I_{CC}.
4. This current applies to the control inputs only and represent the current required to switch internal capacitance at the specified frequency. The I and Y inputs generate no significant AC or DC currents as they transition. This parameter is not tested, but is guaranteed by design.

Switching Characteristics over Operating Range

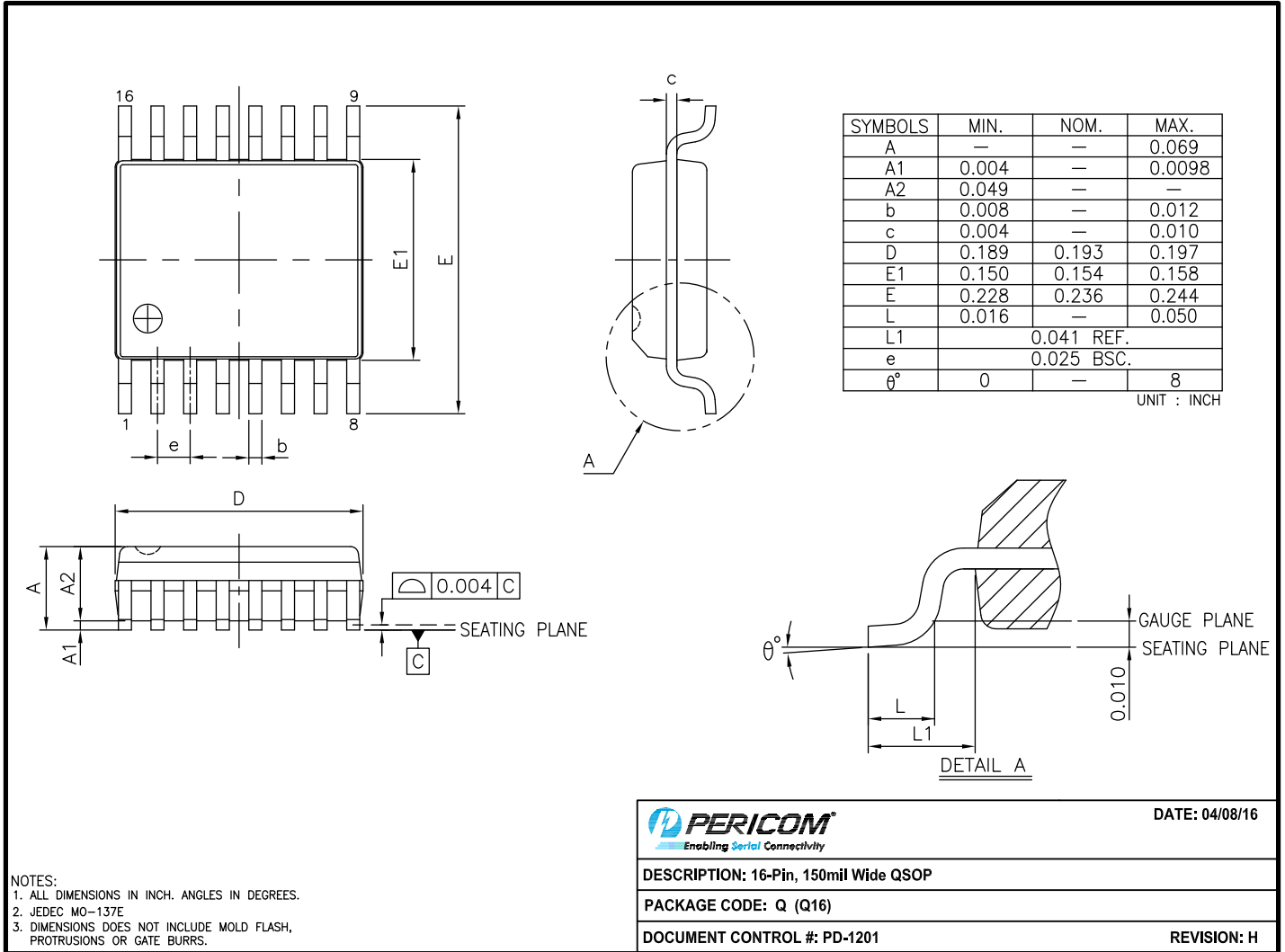
Parameters	Description	Conditions	Com.		Units
			Min.	Max.	
t _Y	Propagation Delay ^(1,2) In to Yn	C _L = 50pF R _L = 500Ω		0.25	ns
t _{SY}	Bus Select Time Sn to Yn		0.5	5.2	
t _{PZH} t _{PZL}	Bus Enable Time \overline{E} to Yn		0.5	4.8	
t _{PHZ} t _{PLZ}	Bus Disable Time \overline{E} to Yn		0.5	5.0	

Notes:

1. This parameter is guaranteed but not tested on Propagation Delays.
2. The bus switch contributes no propagational delay other than the RC delay of the On-Resistance of the switch and the load capacitance. The time constant for the switch alone is of the order of 0.25ns for 50pF load. Since this time constant is much smaller than the rise/fall times of typical driving signals, it adds very little propagational delay to the system. Propagational delay of the bus switch when used in a system is determined by the driving circuit on the driving side of the switch and its interaction with the load on the driven side.

PI5C3257

Packaging Mechanical: 16-pin QSOP (Q)



16-0056

PI5C3257

Packaging Mechanical: 16-pin SOIC (W)

SYMBOLS	MIN.	NOM.	MAX.
A	—	—	1.75
A1	0.10	—	0.25
A2	1.00	—	—
b	0.31	—	0.51
c	0.10	—	0.25
D	9.80	9.90	10.0
E	5.80	6.00	6.20
E1	3.80	3.90	4.00
e	1.27 BSC		
L	0.40	—	1.27
h	0.15	—	0.50
θ°	0	—	8

NOTES:
 1. ALL DIMENSIONS IN MILLIMETERS. ANGLES IN DEGREES.
 2. JEDEC OUTLINE : MS-012 AC
 3. DIMENSIONS DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.
 4. THE MIN. DIMENSION OF A2 AND h ARE OUT OF JEDEC SPEC.

DIODES **PERICOM** PRODUCT LINE OF DIODES INCORPORATED
INCORPORATED ENABLING SERIAL CONNECTIVITY

DATE: 06/30/16

DESCRIPTION: 16-Pin, 150mil Wide SOIC

PACKAGE CODE: W

DOCUMENT CONTROL #: PD-1004

REVISION: G

16-0145

Packaging Mechanical: 16-pin TSSOP (L)

SYMBOLS	MIN.	NOM.	MAX.
A	—	—	1.20
A1	0.05	—	0.15
A2	0.80	1.00	1.05
b	0.19	—	0.30
c	0.09	—	0.20
D	4.90	5.00	5.10
E1	4.30	4.40	4.50
E	6.20	6.40	6.60
e	0.65 BSC		
L1	1.00 REF		
L	0.45	0.60	0.75
S	0.20	—	—
θ	0°	—	8°

NOTES:
 1. ALL DIMENSIONS IN MILLIMETERS. ANGLES IN DEGREES.
 2. JEDEC MO-153F
 3. DIMENSIONS DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.

16-0061

		DATE: 03/24/16
DESCRIPTION: 16-Pin, 173mil Wide TSSOP		
PACKAGE CODE: L (L16)		
DOCUMENT CONTROL #: PD-1310		REVISION: G

Note: For latest package info, please check: <http://www.pericom.com/support/packageing/packageing-mechanicals-and-thermal-characteristics/>

Ordering Information

Ordering Code	Packaging Code	Package Description
PI5C3257QE	Q	16-pin, 150-mil Wide (QSOP)
PI5C3257QEX	Q	16-pin, 150-mil Wide (QSOP), Tape & Reel
PI5C3257WE	W	16-pin, 150-mil Wide (SOIC)
PI5C3257WEX	W	16-pin, 150-mil Wide (SOIC), Tape & Reel
PI5C3257LE	L	16-pin, 173-mil Wide (TSSOP)
PI5C3257LEX	L	16-pin, 173-mil Wide (TSSOP), Tape & Reel

Notes:

- Thermal characteristics can be found on the company web site at www.pericom.com/packageing/
- E = Pb-free & Green
- Adding an X suffix = Tape/Reel

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